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# FDT458P

# 30V P-Channel PowerTrench MOSFET

### **General Description**

This P-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers, and battery chargers.

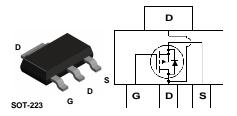
These MOSFETs feature faster switching and lower gate charge than other MOSFETs with comparable  $R_{\text{DS(ON)}}$  specifications.

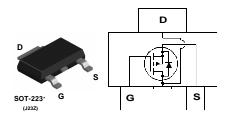
#### **Applications**

- · Battery chargers
- Motor drives

#### **Features**

- 3.4 A, -30 V.  $R_{DS(ON)} = 130 \text{ m}\Omega$  @  $V_{GS} = 10 \text{ V}$  $R_{DS(ON)} = 200 \text{ m}\Omega$  @  $V_{GS} = 4.5 \text{ V}$
- · Fast switching speed
- Low gate charge (2.5 nC typical)
- High performance trench technology for extremely low R<sub>DS(ON)</sub>
- High power and current handling capability in a widely used surface mount package





## Absolute Maximum Ratings T<sub>A</sub>=25°C unless otherwise noted

| Symbol                            | Parameter                                     |         | Ratings     | Units |
|-----------------------------------|---|---------|-------------|-------|
| V <sub>DSS</sub>                  | Drain-Source Voltage                          |         | - 30        | V     |
| V <sub>GSS</sub>                  | Gate-Source Voltage                           |         | ±20         | V     |
| I <sub>D</sub>                    | Drain Current - Continuous (No                | ote 1a) | 3.4         | Α     |
|                                   | - Pulsed                                      |         | 10          |       |
| P <sub>D</sub>                    | Maximum Power Dissipation (No                 | ote 1a) | 3.0         | W     |
|                                   | (No   | ote 1b) | 1.3         |       |
|                                   | (No   | ote 1c) | 1.1         |       |
| T <sub>J</sub> , T <sub>STG</sub> | Operating and Storage Junction Temperature Ra | ange    | -55 to +150 | °C    |

## **Thermal Characteristics**

| R <sub>0JA</sub> | Thermal Resistance, Junction-to-Ambient | (Note 1a) | 42 | °C/W |
|------------------|---|-----------|----|------|
| R <sub>0JC</sub> | Thermal Resistance, Junction-to-Case    | (Note 1)  | 12 | °C/W |

**Package Marking and Ordering Information** 

|                |         | _         |            |            |
|----------------|---------|-----------|------------|------------|
| Device Marking | Device  | Reel Size | Tape width | Quantity   |
| 458P           | FDT458P | 13"       | 12mm       | 2500 units |

| Symbol                                | Parameter   | Test Conditions  | Min        | Тур               | Max               | Units |
|---------------------------------------|---|--|------------|-------------------|-------------------|-------|
| Off Char                              | acteristics   |  |            | ı                 |                   | l     |
| BV <sub>DSS</sub>                     | Drain-Source Breakdown Voltage                        | $V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$   | -30        |                   |                   | V     |
| ΔBV <sub>DSS</sub><br>ΔT <sub>J</sub> | Breakdown Voltage Temperature Coefficient             | $I_D = -250 \mu\text{A}$ , Referenced to 25°C  |            | -23               |                   | mV/°C |
| I <sub>DSS</sub>                      | Zero Gate Voltage Drain Current                       | $V_{DS} = -24 \text{ V},  V_{GS} = 0 \text{ V}$  |            |                   | -1                | μΑ    |
| I <sub>GSSF</sub>                     | Gate-Body Leakage, Forward                            | $V_{GS} = -25 \text{ V},  V_{DS} = 0 \text{ V}$  |            |                   | 100               | nA    |
| I <sub>GSSR</sub>                     | Gate-Body Leakage, Reverse                            | $V_{GS} = -25 \text{ V},  V_{DS} = 0 \text{ V}$  |            |                   | -100              | nA    |
| On Char                               | acteristics (Note 2)                                  |  |            |                   |                   |       |
| V <sub>GS(th)</sub>                   | Gate Threshold Voltage                                | $V_{DS} = V_{GS}, I_D = -250 \mu A$  | -1         | -1.8              | -3                | V     |
| $\Delta V_{GS(th)} \over \Delta T_J$  | Gate Threshold Voltage<br>Temperature Coefficient     | $I_D$ = -250 $\mu$ A, Referenced to 25°C   |            | 4                 |                   | mV/°C |
| R <sub>DS(on)</sub>                   | Static Drain–Source<br>On–Resistance                  | V <sub>GS</sub> = -10 V, l <sub>D</sub> = -3.4 A<br>V <sub>GS</sub> = -4.5 V, l <sub>D</sub> = -2.7 A<br>V <sub>GS</sub> =-10 V, l <sub>D</sub> =-3.4 A, T <sub>J</sub> =125°C |            | 105<br>157<br>147 | 130<br>200<br>210 | mΩ    |
| I <sub>D(on)</sub>                    | On-State Drain Current                                | $V_{GS} = -10 \text{ V}, \qquad V_{DS} = -5 \text{ V}$   | <b>-</b> 5 |                   |                   | Α     |
| <b>g</b> FS                           | Forward Transconductance                              | $V_{DS} = -5 \text{ V}, \qquad I_{D} = -3.4 \text{ A}$   |            | 3                 |                   | S     |
| Dynamic                               | Characteristics                                       |  |            | •                 |                   | •     |
| Ciss                                  | Input Capacitance                                     | $V_{DS} = -15 \text{ V},  V_{GS} = 0 \text{ V},$   |            | 205               |                   | pF    |
| Coss                                  | Output Capacitance                                    | f = 1.0 MHz  |            | 55                |                   | pF    |
| C <sub>rss</sub>                      | Reverse Transfer Capacitance                          |  |            | 26                |                   | pF    |
| Switchin                              | g Characteristics (Note 2)                            |  |            | ı                 | ı                 | I     |
| t <sub>d(on)</sub>                    | Turn-On Delay Time                                    | $V_{DD} = -15 \text{ V}, \qquad I_D = -1 \text{ A},$   |            | 4.5               | 9                 | ns    |
| t <sub>r</sub>                        | Turn-On Rise Time                                     | $V_{GS} = -10 \text{ V}, \qquad R_{GEN} = 6 \Omega$  |            | 12.5              | 23                | ns    |
| t <sub>d(off)</sub>                   | Turn-Off Delay Time                                   |  |            | 11                | 20                | ns    |
| t <sub>f</sub>                        | Turn-Off Fall Time                                    |  |            | 2                 | 4                 | ns    |
| Qg                                    | Total Gate Charge                                     | $V_{DS} = -15 \text{ V},  I_{D} = -3.4 \text{ A},$   |            | 2.5               | 3.5               | nC    |
| Q <sub>gs</sub>                       | Gate-Source Charge                                    | V <sub>GS</sub> = -10 V  |            | 0.7               |                   | nC    |
| Q <sub>gd</sub>                       | Gate-Drain Charge                                     |  |            | 1                 |                   | nC    |
| Drain-So                              | ource Diode Characteristics                           | and Maximum Ratings  |            | •                 | •                 |       |
| ls                                    | Maximum Continuous Drain-Source Diode Forward Current |  |            |                   | -2.5              | Α     |
| V <sub>SD</sub>                       | Drain–Source Diode Forward<br>Voltage                 | $V_{GS} = 0 \text{ V},  I_S = -2.5 \text{ A}$ (Note 2)   |            | -0.8              | -1.2              | V     |

#### Notes

R<sub>0,N</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R<sub>0,C</sub> is guaranteed by design while R<sub>0,CA</sub> is determined by the user's board design.



a) 42°C/W when mounted on a 1in² pad of 2 oz copper



b) 95°C/W when mounted on a .0066 in² pad of 2 oz copper



c) 110°C/W when mounted on a minimum pad.

<sup>2.</sup> Pulse Test: Pulse Width  $< 300 \mu s$ , Duty Cycle < 2.0%

# **Typical Characteristics**

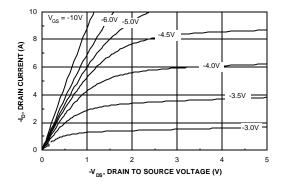


Figure 1. On-Region Characteristics.

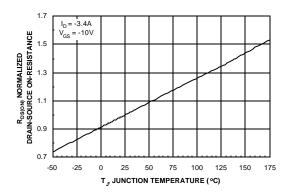


Figure 3. On-Resistance Variation with Temperature.

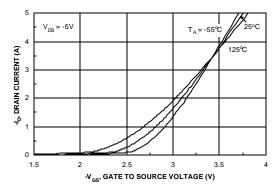


Figure 5. Transfer Characteristics.

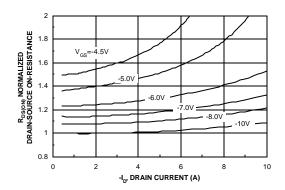


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

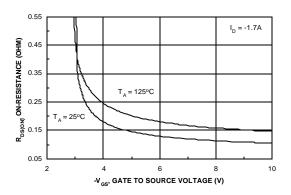


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

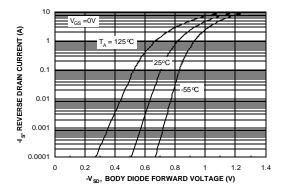
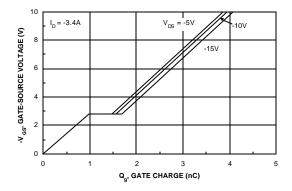


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

# **Typical Characteristics**



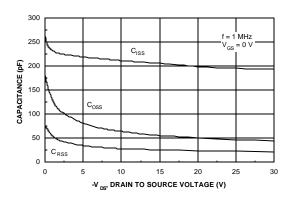
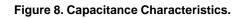
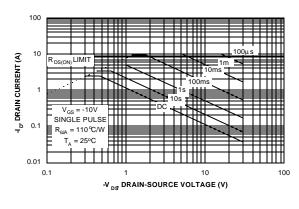


Figure 7. Gate Charge Characteristics.





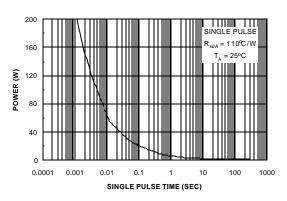


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

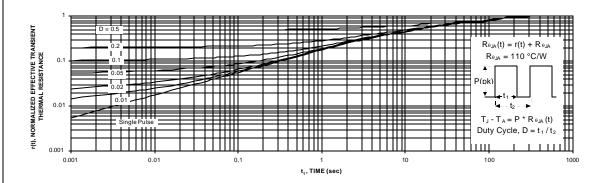
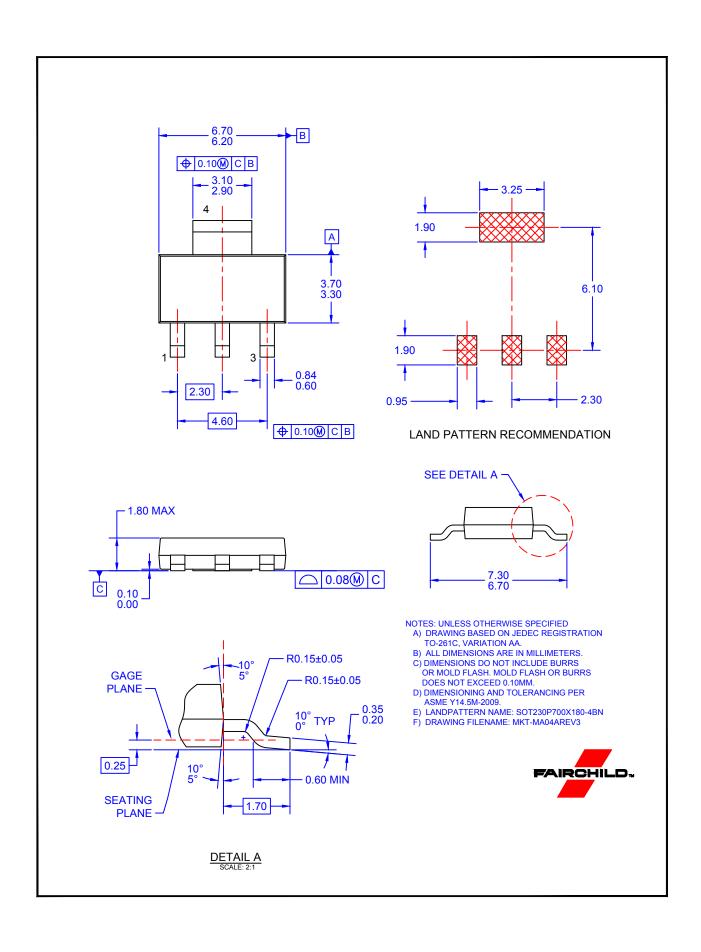


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c. Transient thermal response will change depending on the circuit board design.



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